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IME03-005

March 11, 2005

To: Mail Stop: Application Number
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

From: Stephen B. Ackerman

Subject: Serial No.: 10/748,736
Filing Date: 12/30/2003
Inventor: Ee Hua Wong, Ranjan S/O/ Rajoo, Poi Siong Teo
Title: Wafer Level Super Stretch Solder

REQUEST TO CORRECT FILING RECEIPT

Dear Sir:

On the copy of the enclosed Filing Receipt, there is an error in "Applicant(s)" field. The errors is Ee Hua Wong, Singapor, Singapore. The correction is **Ee Hua Wong, Singapore, Singapore**

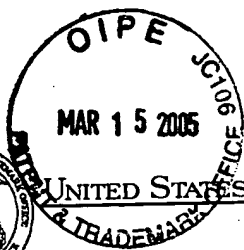
Please make the necessary changes to correct the error on the Filing Receipt.

If there are any questions, please contact the undersigned attorney at (845) 452-5863. Thank you for your attention to this matter.

Respectfully Submitted,

Stephen B. Ackerman, Reg. No. 37,761

AUG. 14 2004



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APPL NO.	FILING OR 371 (c) DATE	ART UNIT	FIL FEE REC'D	ATTY. DOCKET NO	DRAWINGS	TOT CLMS	IND CLMS
10/748,736	12/30/2003	1725	1460	IME03-005	6	32	7

CONFIRMATION NO. 7541

UPDATED FILING RECEIPT



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Date Mailed: 08/12/2004

Receipt is acknowledged of this regular Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Filing Receipt Corrections, facsimile number 703-746-9195. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

Applicant(s)

Ee Hua Wong, Singapor, SINGAPORE;
 Ranjan S/O Rajoo, Singapore, SINGAPORE;
 Poi Siong Teo, Singapore, SINGAPORE;

Domestic Priority data as claimed by applicant**Foreign Applications****If Required, Foreign Filing License Granted: 05/06/2004****Projected Publication Date: 06/30/2005****Non-Publication Request: No****Early Publication Request: No****Title**

Wafer level super stretch solder

Preliminary Class

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